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FOR IMMEDIATE RELEASE

High Density Packaging User Group Announces Nippon Denkai Membership

Cave Creek, Arizona January 21, 2021. High Density Packaging (HDP) User Group is pleased to announce that Nippon Denkai has become our newest member.

"Nippon Denkai is excited to be a member of the HDP User Group. We look forward to learning from our member partners through the collaborative problem solving approach fostered by the HDP team. By contributing our knowledge in copper foils, we believe that our participation will assist in projects related to printed circuit board processing, reliability, and signal integrity.", said Michael Coll, COO at Denkai America.

"It is an honor and a privilege to have Nippon Denkai join the outstanding companies working on HDP User Group projects. Their expertise and capability in copper foil manufacturing will contribute significantly to several of our projects, such as our copper surface vs. loss project, which is focused on high-speed signal integrity", said Larry Marcanti, Executive Director of HDP User Group.

About Nippon Denkai

Nippon Denkai Ltd., along with Denkai America Inc., have been manufacturing electrodeposited copper foil for over 60 years. We lead the industry by providing cutting-edge copper electroplating and advanced surface treatment capabilities. Our high-quality electrodeposited copper foils can be found in the most challenging printed circuit board (PCB), industrial, and lithium ion battery (LiB) applications. Nippon Denkai is headquartered in Chikusei, Ibaraki Prefecture, Japan. Denkai America is located in Camden, South Carolina.

More information can be found at: <u>www.nippon-denkai.co.jp</u> and <u>www.denkaiamerica.com</u>



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About HDP User Group

HDP User Group (<u>www.hdpug.org</u>), a global research and development organization based in Cave Creek Arizona, is dedicated to reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly. This international industry-led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP User Group maintains additional offices in Austin Texas, and Singapore.

For more information, visit HDP User Group on the Internet at <u>www.hdpug.org</u> or contact Darryl Reiner at darrylr@hdpug.org, phone number +1 480-951-1963.